Enabling Technologies: Wireless and Mobile Connectivity

AN IDC CONTINUOUS INTELLIGENCE SERVICE

IDC’s Enabling Technologies: Wireless and Mobile Connectivity service provides a wholistic view of the connectivity semiconductor market across wireless connectivity (Bluetooth, NFC, WiFi), LPWA, and mobile connectivity (2G, 3G, 4G, and 5G) technologies. Historical and market forecasts are included for baseband, transceiver, and RF chipset shipments and revenue by dozens of end-market segments across end-user and IoT products in various vertical markets. This research will answer questions about which technologies will survive as they evolve and encroach on the space typically occupied by competing or complementary technologies.

Markets and Subjects Analyzed

- Wireless connectivity baseband chips — shipment and revenue forecasts and market share
- Wireless connectivity includes WiFi, Bluetooth, NFC, and GNSS
- Mobile connectivity baseband chips — shipment and revenue forecasts and market share
- Mobile connectivity includes 2G, 3G, 4G, and 5G air interfaces
- RF components and front-end products — revenue and market share

Core Research

- Worldwide Wireless Connectivity Chipset Market Shares
- Worldwide Mobile Connectivity Chipset Market Shares
- Worldwide Wireless Connectivity Technologies Forecast, 2018–2022
- Worldwide Mobile Connectivity Technologies Forecast, 2018–2022

Key Questions Answered

1. How will evolving technologies take share of existing technologies in certain product types?
2. How is the revenue mix shifting from baseband and transceivers to RF front-end components, especially with LTE-A Pro and 5G?
3. Which are the dominant wireless connectivity baseband vendors? Mobile baseband vendors? RF front-end vendors?
4. What are the trends for standalone, combo, and integrated wireless connectivity?
5. Which WiFi protocols are dominant in which product types?
6. What are the trends for chipset vendors supporting WiFi infrastructure and set-top boxes in terms of mesh networking, MIMO, and MU-MIMO?

Companies Analyzed

This service reviews strategies, market positioning, and future direction of several providers in the wireless and mobile connectivity chipset market, including:

AMD, ARM, Apple, Broadcom, Cypress Semiconductor, Dialog Semiconductor, Huawei, Intel, Lattice Semiconductor, Marvell, MediaTek, Murata, Nordic Semiconductor, Peraso, Qorvo, Qualcomm, Quanterra, Silicon Labs, Skyworks, Texas Instruments, and Tsinghua

In addition to the insight provided in this service, IDC may conduct research on specific topics or emerging market segments via research offerings that require additional IDC funding and client investment. To learn more about the analysts and published research, please visit: Enabling Technologies: Wireless and Mobile Connectivity.